



FOR IMMEDIATE RELEASE

Ambassador of India to Estonia Visits Brandner Electronics OÜ in Paide

Visit highlights growing India-Estonia cooperation in advanced electronics manufacturing



H.E. Mr Ashish Kumar Sinha, Ambassador of India to the Republic of Estonia, with Dr Eswara Rao Nandam during the Ambassador's visit to Brandner Electronics OÜ in Paide on 25 September 2026.

Paide, Estonia - 26 September 2026. Brandner Electronics OÜ was honoured to receive H.E. Mr Ashish Kumar Sinha, Ambassador of India to the Republic of Estonia, at its printed circuit board manufacturing facility in Paide on Friday, 25 September 2026.

Arranged through the Commerce Wing of the Embassy of India in Tallinn, the visit gave the Ambassador a first-hand view of Brandner's manufacturing operations and its capabilities in standard, multilayer, high-density interconnect and aluminium printed circuit boards.

The Ambassador was received by Dr Eswara Rao Nandam, Group Chairman of Polymatech, together with Mr Vishaal Nandam, Managing Board Member of Brandner Electronics OÜ. The facility tour was conducted by Ms Tarja Rapala-Virtanen, Chief Executive Officer, Mr Urmas Aruoja, Managing Director, and members of Brandner's production team.

25 SEPTEMBER 2026	INDIAN-BACKED	2027
Ambassador's visit to Paide	Advanced manufacturing in Estonia	Next phase of capability expansion

Manufacturing capability and the next phase



H.E. Mr Ashish Kumar Sinha examines a PCB production panel during his tour of the Paide facility, accompanied by Dr Eswara Rao Nandam and members of the Brandner team.

During the visit, Brandner presented its current operations and phased development plan for Estonia to His Excellency the Ambassador. Brandner has commenced PCB production for Polymatech's vein finders and is developing PCBs for NANORAA smartphones. Following successful prototype validation, manufacturing capacity and process capabilities will be expanded for volume production.

The near-term programme includes further PCB capability additions, surface-mount technology module assembly and preparations for silicon carbide semiconductor packaging and power modules for electric-vehicle applications from calendar year 2027. The group is also evaluating sapphire crystal growth and processing as part of the longer-term development of the Paide site.

LONG-TERM COMMITMENT

Commitment to Estonia

The Polymatech group's investment in Brandner Electronics OÜ has been made through AEIM Pte. Ltd., Singapore. It has supported the acquisition and operational development of the Paide facility, preserved advanced European manufacturing capability and established a platform for continued expansion in Estonia.

"We are deeply honoured by His Excellency's visit to our Paide facility. Estonia offers a skilled workforce, a transparent business environment and a strong foundation for advanced manufacturing. The visit has encouraged our entire team as we build the next phase of Brandner in Estonia."

- Dr Eswara Rao Nandam, Group Chairman, Polymatech

"It was enriching to visit the Brandner Electronics facility in Paide; a strategic manufacturing base marks an important milestone in growing bilateral commercial ties between India and Estonia, looking forward to its exponential growth in near future."

- H.E. Mr Ashish Kumar Sinha, Ambassador of India to the Republic of Estonia

A commemorative moment



H.E. Mr Ashish Kumar Sinha plants a commemorative tree during his visit to Brandner Electronics OÜ in Paide, accompanied by Dr Eswara Rao Nandam and members of the Brandner team.

The visit concluded with discussions on strengthening commercial and industrial links between India and Estonia. Brandner intends to combine Estonia's engineering and manufacturing strengths with the Polymatech group's international product platforms and access to the Indian market.

About Brandner Electronics OÜ

Brandner Electronics OÜ (registry code 17117350) is a printed circuit board manufacturer based in Paide, Järva County, Estonia. The company manufactures standard, multilayer, high-density interconnect and aluminium PCBs. Brandner has commenced production of PCBs for Polymatech's Vein Finders and is developing mobile-phone PCBs, while adding further capabilities in module assembly and advanced electronics manufacturing. Visit www.brandner.ee.

About AEIM Pte. Ltd.

AEIM Pte. Ltd. is the Singapore-based international headquarters and operating company of the Polymatech group. Its activities include advanced electronics manufacturing, semiconductor packaging, memory-module assembly, medical products and other application-specific integrated circuits (ASICs). The Polymatech group's investment in Brandner Electronics OÜ has been made through AEIM Pte. Ltd.

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Brandner Electronics OÜ's PCB manufacturing facility in Paide, Estonia.

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